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(54) **SEMICONDUCTOR DEVICE**

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(57) Abstract:

PURPOSE: To improve product yield without mechanical stress at a solder bump, deformation, damage, short-circuit between the bumps by arranging a flexible sheet between a substrate and the bumps.

CONSTITUTION: A flexible sheet 17 is arranged between solder bumps 10 and a solder connection part 12. The sheet 17 is formed of a material which can absorb mechanical strain in the case of solder connecting such as low thermal expansion polyimide. It is deviated to a connecting direction so that solder bumps 10 are not opposed to the part 12. If the bumps 10 and the part 12 are deviated at the positions, a pattern of conductor wiring for connecting both is formed on the sheet 17. Thus, since the bumps 10 of a semiconductor chip 9 are merely brought into contact with the sheet 17 but not brought into pressure contact with a member at the side of a substrate 11, the bumps 10 do not receive mechanical stress, and deformation and connection between the bumps do not occur.

